

Notice of References Cited	Application/Control No. 10/697,898	Applicant(s)/Patent Under Reexamination KAUTZ ET AL.	
	Examiner Christian Wilson	Art Unit 2824	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,377,464	04-2002	Hashemi et al.	361/760
	B	US-6,642,064	11-2003	Terrill et al.	438/15
	C	US-6,677,668	01-2004	Lin, Paul T.	257/685
	D	US-6,700,196	03-2004	Kautz et al.	257/723
	E	US-6,707,141	03-2004	Akram, Salman	257/686
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Cotton <i>et al.</i> , Design and Development Challenges for Complex Laminate Multichip Modules, <i>International Conf. Multichip Modules</i> , (Apr 1997) 196.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.